EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1008	hasebe-hazuhide.in. or okada-mitsuhiro.in. or chiba-takashi.in. or ogawa-jun.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 09:06
S2	2	"20060213539"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 09:06
S3	26	("20030010354" | "3865652" | "5129958" | "5963834" | "6095158" | "6121161" | "6325857" | "6375756" | "6444037" | "6468903" | "6872323" | "6942892").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 09:36
S4	1210	load$3 with (substrate or semiconductor or wafer) with (temperature and pressure)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 10:21
S5	372	438/905.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 10:24
S6	3	S4 S5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 10:24
S7	331	S4 "438".clas.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 10:30
S8	64	load$3 with (substrate or semiconductor or wafer) near5 (temperature and (pressure with vacuum))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 10:37

S9	6296	loading near2 temperature	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 10:55
S10	51	load$3 with (substrate or semiconductor or wafer) near5 (room with temperature) same(pressure with vacuum)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:03
S11	277	load$3 with (substrate or semiconductor or wafer) near5 (room with temperature)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:06
S12	1366	438/758.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:28
S13	274	438/630.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:28
S14	372	438/905.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:28
S15	816	134/1.1.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:28
S16	2715	134/1.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:29
S17	1397	134/22.1.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:29

S18	764	134/22.11.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:29
S19	797	134/22.12.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:29
S20	2904466	@pd>="20070502"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:29
S21	254	(S12 or S13 or S14) S20	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 11:29
S22	94	load$3 with (substrate or semiconductor or wafer) near5 (room with temperature) same (pressure)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 12:26
S23	277	load$3 with (substrate or semiconductor or wafer) near5 (room with temperature)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 12:46
S24	12	S23.clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 13:06
S25	3	load$3 with (substrate or semiconductor or wafer) near5 (room with temperature) with advantage	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/22 13:13
S26	277	load$3 with (substrate or semiconductor or wafer) near5 (room with temperature)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:17

S27	93	unload$3 with (substrate or semiconductor or wafer) near5 (room with temperature)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:19
S28	35	S26 S27	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:19
S29	48	("20010021000" | "3978580" | "4094058" | "4653864" | "4691995" | "4775225" | "5247377" | "5263888" | "5379139" | "5406989" | "5499128" | "5507323" | "5511591" | "5539545" | "5548429" | "5642214" | "5680189" | "5692873" | "5742370" | "5757451" | "5765889" | "5852484" | "5854664" | "5861932" | "5875922" | "5952676" | "5956112" | "6001203" | "6011609" | "6016178" | "6016181" | "6055035" | "6062241" | "6068316" | "6072157" | "6152677" | "6163357" | "6219126" | "6226067" | "6236445" | "6304306" | "6304311" | "6322116" | "6337730" | "6414733" | "6634686").PN. OR ("6860533").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2008/07/24 09:25
S30	662	unload$3 with (substrate or semiconductor or wafer) near5 temperature	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:27
S31	42	S26 S30	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:27
S32	7	S31 not S28	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:27

S33	2	"6143080".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:30
S34	890	load$3 with (substrate or semiconductor or wafer or (work adj piece)) with ((room with temperature) or (temperature deg$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:34
S35	190	unload$3 with (substrate or semiconductor or wafer or (work adj piece)) with ((room with temperature) or (temperature deg$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:35
S36	104	S34 S35	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:35
S37	31864939	@pd<"20030325"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:35
S38	46	S36 S37	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:35
S39	37	S36 S37 (pressure or vacuum)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:36
S40	312750	load$3 with (pressure or vacuum)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:39
S41	9	S38 S40	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:39

S42	7970	118/715.ccls. or 118/724. ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:42
S43	54	S34 S42	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:43
S44	20	S43 S37	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:45
S45	9	S43 S37 unload$5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/07/24 09:49

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